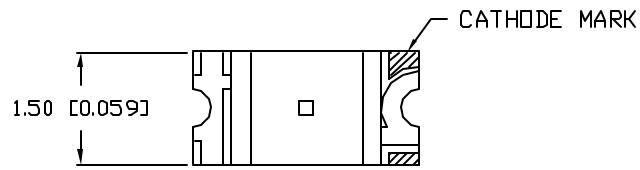
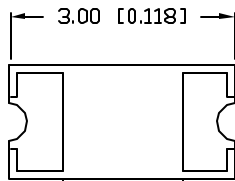
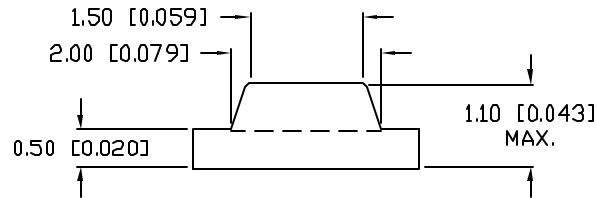


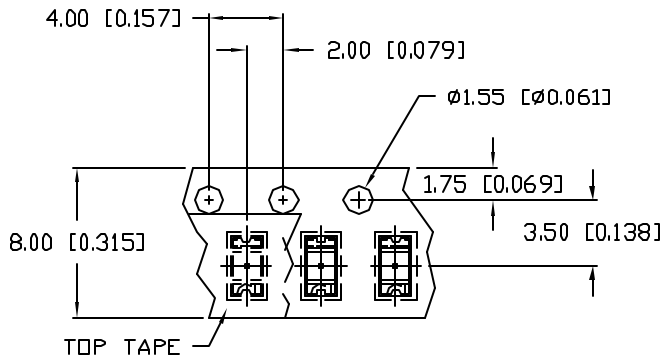
UNCONTROLLED DOCUMENT



☐ ANODE ◯ CATHODE

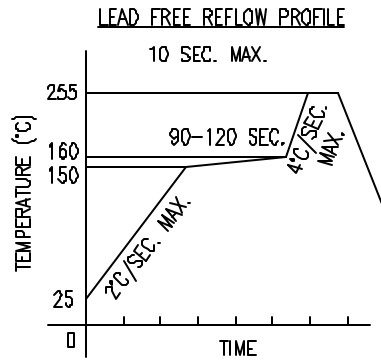
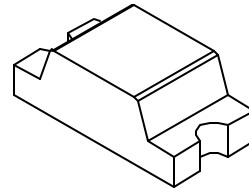


1.60 [0.063]



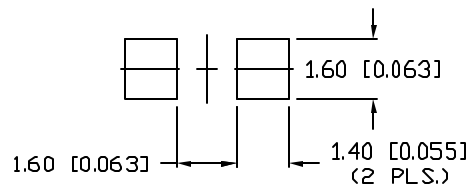
☐ TAPE FEED DIRECTION →

*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), X.X=±0.5 (±0.020), X.XX=±0.25 (±0.010), X.XXX=±0.127 (±0.005). LEAD SIZE=±0.05 (0.002), LEAD LENGTH=±0.75 (±0.030). MIN= ^{+DECIMAL PRECISION} -0.00 MAX= ^{+0.00} -DECIMAL PRECISION



TOTAL TIME ABOVE 220°C IS 60 SECONDS MAX.

RECOMMENDED SOLDER PAD LAYOUT



PART NUMBER
SML-LX1106SRC-TR

REV.
C

REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE
A	E.C.N. #10967.	3.14.03
B	E.C.N. #11318 & 11148.	3.22.06
C	E.C.N. #11325.	4.19.05

ELECTRO-OPTICAL CHARACTERISTICS $T_A=25^\circ\text{C}$ $I_f=20\text{mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		660		nm	
FORWARD VOLTAGE		1.7	2.2	V _f	
REVERSE VOLTAGE	4.0			V _r	I _f =100µA
AXIAL INTENSITY		70		med	I _f =20mA
VIEWING ANGLE		140		2x theta	
EMITTED COLOR:	RED				
EPOXY LENS FINISH:	WATER CLEAR				

LIMITS OF SAFE OPERATION AT 25°C

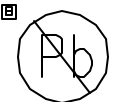
PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	200	mA
STEADY CURRENT	30	mA
POWER DISSIPATION	100	mW
DERATE FROM 25°C	-1.2	mW/°C
OPERATING TEMP.	-30 TO +85	°C
STORAGE TEMP.	-40 TO +85	°C

* t < 10µs

NOTES:

☐ 1. CATHODE IS ORIENTED TOWARDS THE TAPE SPROCKET HOLE.

☐ CAUTION: MOISTURE SENSITIVE DEVICE PER JEDEC LEVEL 4 STANDARDS



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TW WEB: www.lumex.com.tw

3mm x 1.5mm SURFACE MOUNT LED,
660nm SUPER RED LED,
WATER CLEAR LENS, TAPE AND REEL

RELIABILITY NOTE
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY: BC	CHECKED BY:	APPROVED BY:	DATE: 1.8.01
			PAGE: 1 OF 1
			SCALE: N/A